Created Date: 31/03/04	SPÉCIFICATION	
Ref. : Alloy	<u>Sn100 SP</u>	mloo
<b>Updated:</b> 10/05/06	LEAD FREE ALLOY	

## 1 - GENERAL CHARACTERISTICS:

Eutectic alloy for soldering printed circuits, produced from very high quality metals. This alloy is especially developed with special addition of components to reduce oxide production and to increase the fluidity of the melted solder. It is used as additive in soldering baths with Sn99CuSP, to reduce copper content dude to the contamination by coppered PCB's

# 2 – <u>CHEMICAL CHARACTERISTICS</u>:

2.1 Amount of Tin : 99.8 % +/- 0.2 % 2.2 Amount of copper : 0.2 % +/- 0.2 %

2.3 Tin for first melting, copper purity > 99.99%

2.4 Maximum content of impurities: see below

Cd	Sb	Bi	Fe	Zn	Al	As	Pb	others
< 0.002	< 0.05	< 0.01	< 0.02	< 0.001	< 0.001	< 0.01	< 0.05	< 0.05
%	%	%	%	%	%	%	%	%

#### 3- PHYSICAL CHARACTERISTICS:

3.1 Melting point  $: 227^{\circ}\text{C} - 229^{\circ}\text{C}$ 

3.2 Working temperature : 250 to 280°C (wave soldering)

3.3 Specific Weight : 7.3

### *4 – <u>SUPPLIED AS</u>* :

4.1 Bars : Extruded Bars or sticks in cartons of 20 Kg.

(Exact Tare weight stated).

4.2 Wire : On spools of 15 Kgs. (others please contact us)

4.3 Quality insurance : Certificates of conformity can be supplied with each lot if required. 4.4 Labelling : Cartons/containers labels show manufactured lot N° and Alloy.

#### 5 - STORAGE:

5.1 - In original packaging, at an average temperature of 20°C.

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